



**Statement of Materials, Construction**

16L-SOICW -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.14156	Cu	7440-50-8	0.13790	30.59162	97.41
				Fe	7439-89-6	0.00333	0.73799	2.35
				Pb	7439-92-1	0.00004	0.00900	0.03
				P	7723-14-0	0.00012	0.02575	0.08
				Zn	7440-66-6	0.00018	0.03926	0.13
2	Die	Silicon Chip	0.00399	Si	7440-21-3	0.00397	0.88073	99.50
3	Die attach material	Conductive Epoxy	0.00051	Epoxy resin	Proprietary	0.00008	0.01697	15.00
				Silver	7440-22-4	0.00040	0.08938	79.00
				Aromatic Amine	Proprietary	0.00003	0.00679	6.00
4	Wire	Gold	0.00050	Au	7440-57-5	0.00050	0.11091	99.99
5	Lead Finish	Alloy	0.00471	Pb	7439-92-1	0.00047	0.10449	10.00
				Sn	7440-31-5	0.00424	0.94039	90.00
6	Encapsulation	Epoxy Resin	0.29950	Fused Silica	60676-86-0	0.25907	57.47221	86.50
				Epoxy resin	29690-82-2	0.01947	4.31872	6.50
				Phenol Resin	9003-35-4	0.01198	2.65767	4.00
				Antimony trioxide	1309-64-4	0.00899	1.99326	3.00
Total Package weight			0.45077					

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%